

TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π -MOSV)

2SK2865

Chopper Regulator, DC/DC Converter and Motor Drive Applications

- Low drain-source ON-resistance : $R_{DS(ON)} = 4.2 \Omega$ (typ.)
- High forward transfer admittance : $|Y_{fs}| = 1.7 S$ (typ.)
- Low leakage current : $I_{DSS} = 100 \mu A$ (max) ($V_{DS} = 600 V$)
- Enhancement mode : $V_{th} = 2.0\text{--}4.0 V$ ($V_{DS} = 10 V, I_D = 1 mA$)

Maximum Ratings ($T_a = 25^\circ C$)

Characteristic		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	600	V
Drain-gate voltage ($R_{GS} = 20 k\Omega$)		V_{DGR}	600	V
Gate-source voltage		V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	2	A
	Pulse ($t = 1 ms$) (Note 1)	I_{DP}	5	A
	Pulse ($t = 100 \mu s$) (Note 1)	I_{DP}	8	A
Drain power dissipation ($T_c = 25^\circ C$)		P_D	20	W
Single-pulse avalanche energy (Note 2)		E_{AS}	93	mJ
Avalanche current		I_{AR}	2	A
Repetitive avalanche energy (Note 3)		E_{AR}	2	mJ
Channel temperature		T_{ch}	150	$^\circ C$
Storage temperature range		T_{stg}	$-55\text{--}150$	$^\circ C$

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	6.25	$^\circ C / W$
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	125	$^\circ C / W$

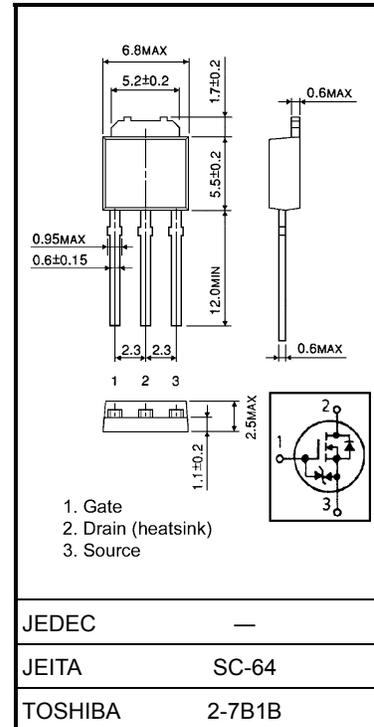
Note 1: Ensure that the channel temperature does not exceed $150^\circ C$.

Note 2: $V_{DD} = 90 V, T_{ch} = 25^\circ C$ (initial), $L = 41 mH, R_G = 25 \Omega, I_{AR} = 2 A$

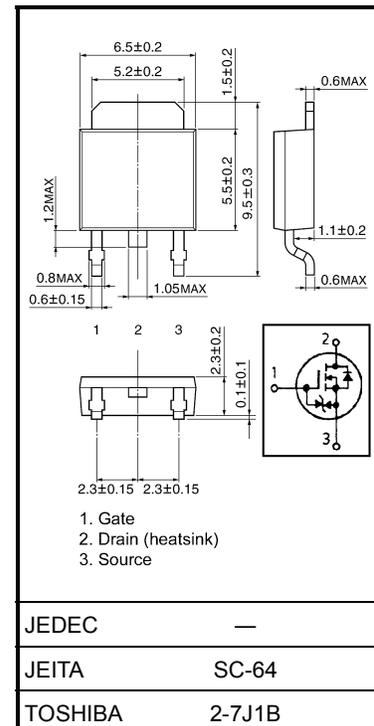
Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

Unit: mm



Weight: 0.36 g (typ.)



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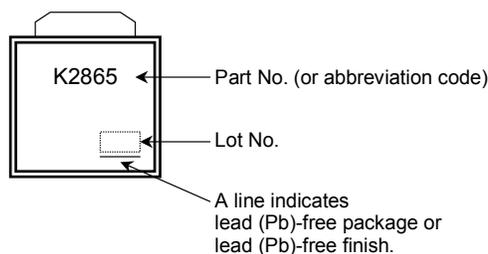
Electrical Characteristics (Ta = 25°C)

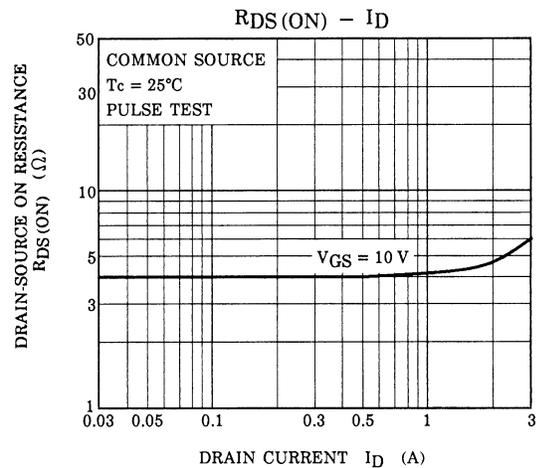
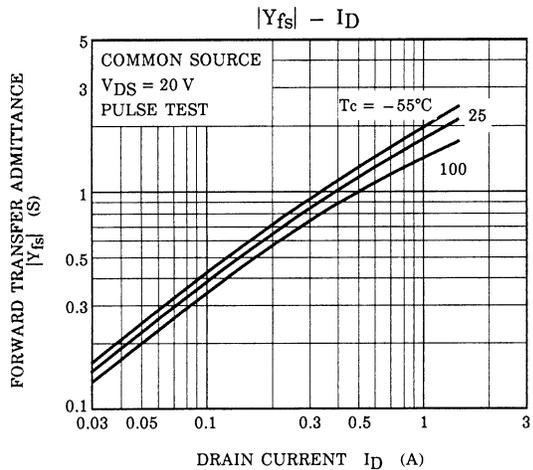
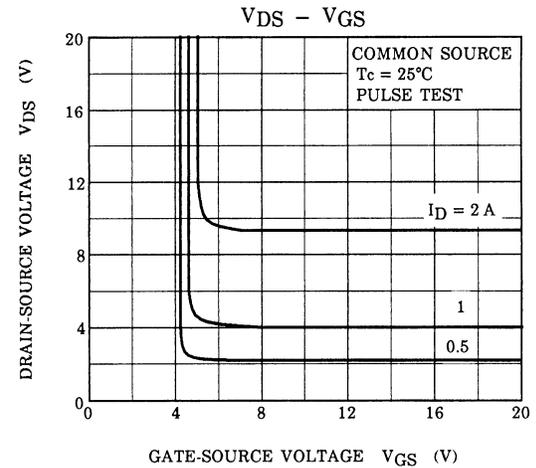
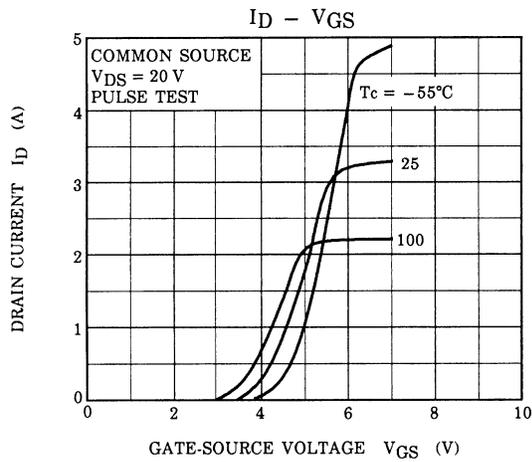
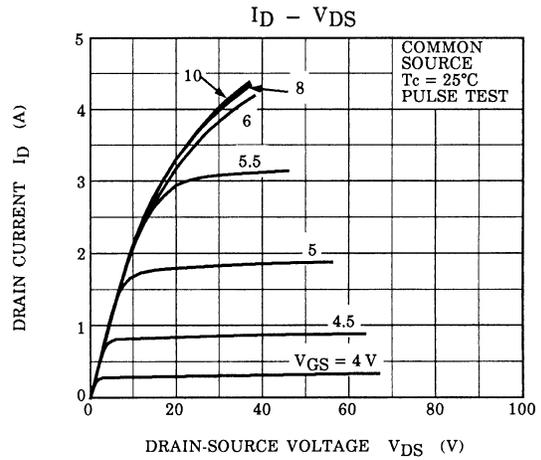
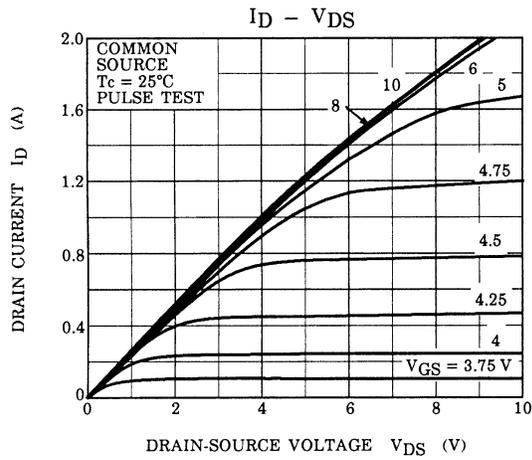
Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 25\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 10	μA
Gate-source breakdown voltage		$V_{(BR)GSS}$	$I_G = \pm 10\ \mu\text{A}, V_{DS} = 0\text{ V}$	± 30	—	—	V
Drain cutoff current		I_{DSS}	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$	—	—	100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	600	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	2.0	—	4.0	V
Drain-source ON-resistance		$R_{DS(ON)}$	$V_{GS} = 10\text{ V}, I_D = 1\text{ A}$	—	4.2	5.0	Ω
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 1\text{ A}$	0.8	1.7	—	S
Input capacitance		C_{iss}	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	380	—	pF
Reverse transfer capacitance		C_{rss}		—	40	—	
Output capacitance		C_{oss}		—	120	—	
Switching time	Rise time	t_r	<p>$V_{GS} = 10\text{ V}$ $V_{GS} = 0\text{ V}$ $50\ \Omega$ $I_D = 1\text{ A}$ $R_L = 200\ \Omega$ $V_{DD} \approx 200\text{ V}$ V_{OUT} $Duty \leq 1\%, t_w = 10\ \mu\text{s}$</p>	—	15	—	ns
	Turn-on time	t_{on}		—	25	—	
	Fall time	t_f		—	20	—	
	Turn-off time	t_{off}		—	80	—	
Total gate charge (gate-source plus gate-drain)		Q_g	$V_{DD} \approx 480\text{ V}, V_{GS} = 10\text{ V}, I_D = 2\text{ A}$	—	9	—	nC
Gate-source charge		Q_{gs}		—	5	—	
Gate-drain ("Miller") charge		Q_{gd}		—	4	—	

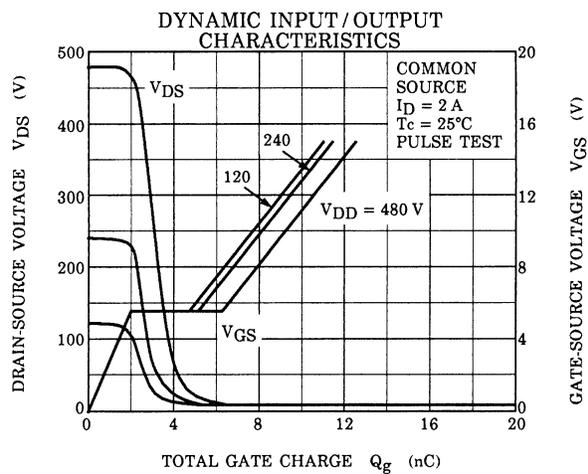
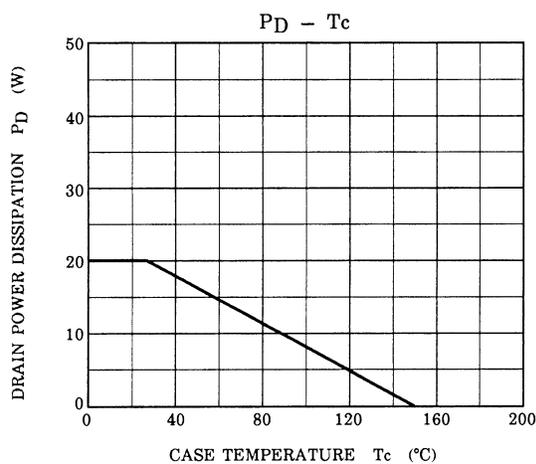
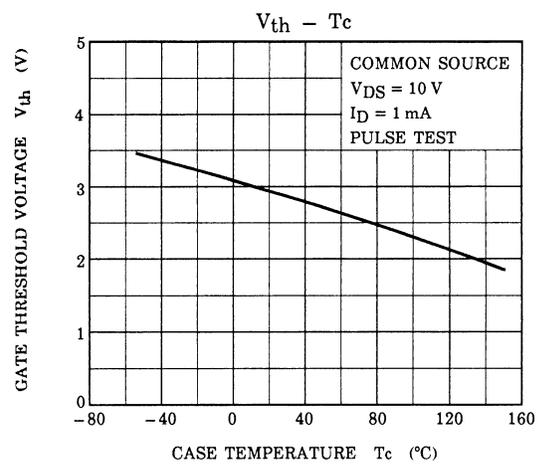
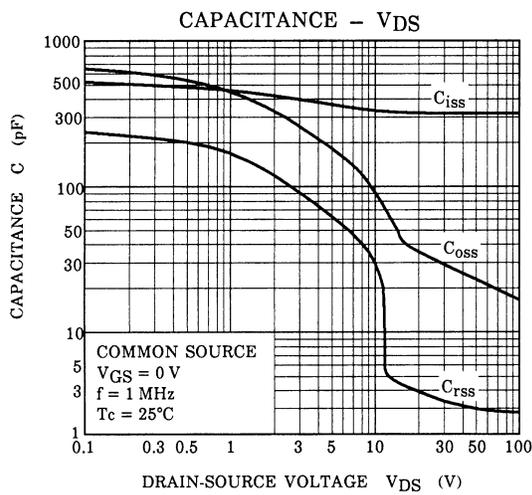
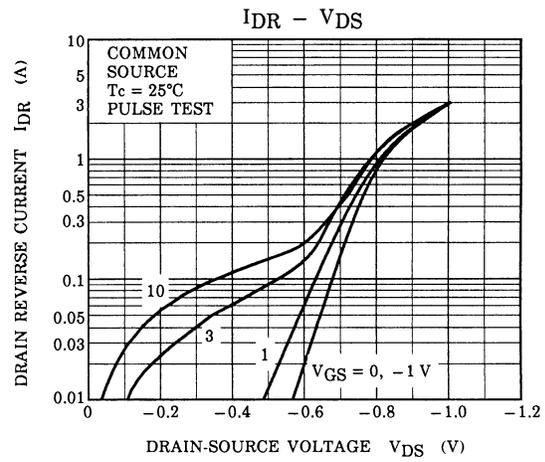
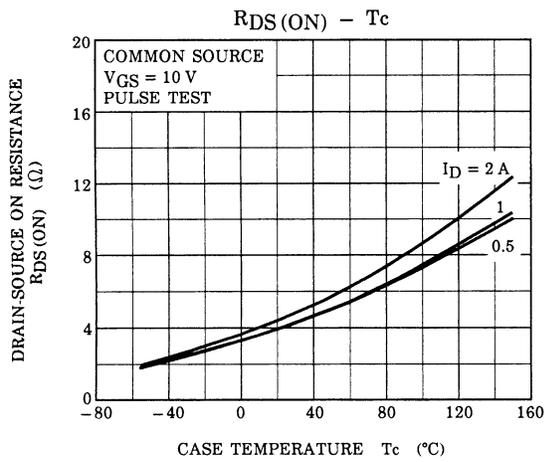
Source-Drain Ratings and Characteristics (Ta = 25°C)

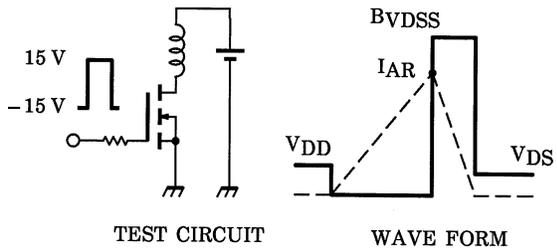
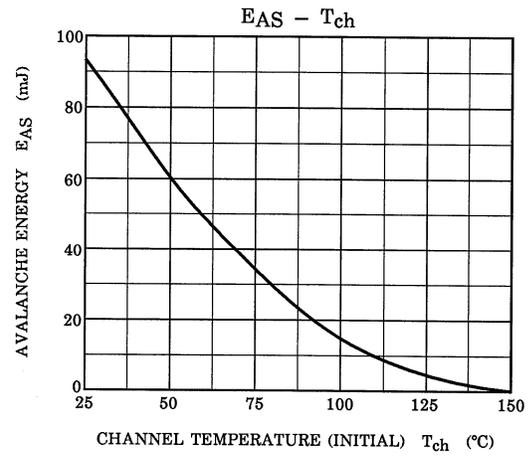
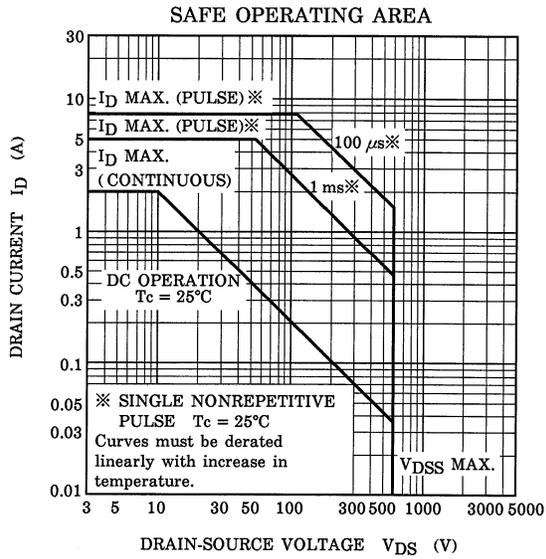
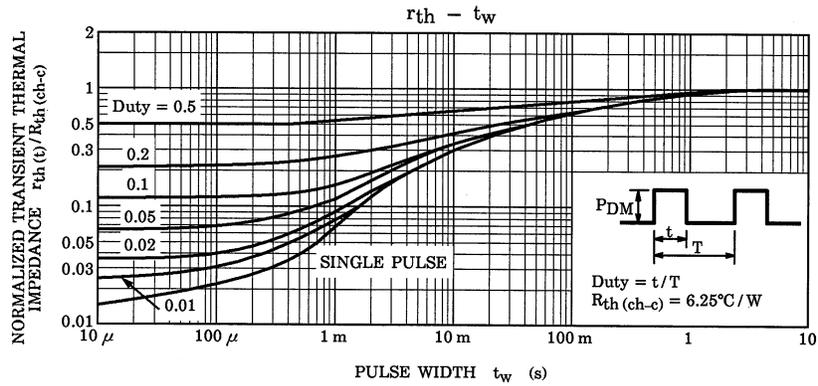
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	2	A
Pulse drain reverse current (Note 1)	I_{DRP}	$t = 1\text{ ms}$	—	—	5	A
	I_{DRP}	$t = 100\ \mu\text{s}$	—	—	8	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 2\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.5	V
Reverse recovery time	t_{rr}	$I_{DR} = 2\text{ A}, V_{GS} = 0\text{ V}$	—	1000	—	ns
Reverse recovery charge	Q_{rr}	$dI_{DR} / dt = 100\text{ A} / \mu\text{s}$	—	3.5	—	μC

Marking









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